



2829

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Modified 9-98

PTO/SB/21 (12-97)

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Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

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# TRANSMITTAL FORM

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BOX: NON-FEE AMENDMENT

Express Mail  
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Application / Conf. No.	09/879,875 / 4969
Filing Date	June 11, 2001
First Named Inventor	Abu K. Eghan
Examiner Name	Evan T. Pert
Group Art Unit	2829
Issue Fee Batch No.	
Attorney Docket Number	X-901 US

## ENCLOSURES (check all that apply)

<input type="checkbox"/> Fee Transmittal Form	<input type="checkbox"/> Assignment Papers (with Recordation Cover Sheet)	<input type="checkbox"/> After Allowance Communication to
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<input type="checkbox"/> Preliminary Amendment	<input type="checkbox"/> Drawing(s)	<input type="checkbox"/> Appeal Communication to Group (Appeal Notice, Brief, Reply Brief)
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## SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

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Attn:	Edel M. Young	
Signature		
Date	October 25, 2002	Charge any additional fees required/credit any overpayment to our Deposit Account Number: 24-0040

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X-901 US  
09/879,875

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Abu K. Eghan et al.

Assignee: Xilinx, Inc.

Title: High Performance Flipchip Package That  
Incorporates Heat Removal With Minimal  
Thermal Mismatch

Serial No.: 09/879,875

File Date: 6/11/01

Examiner: Evan T. Pert

Art Unit: 2829

Docket No.: X-901 US

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BOX NON-FEE AMENDMENT  
COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

AMENDMENT IN RESPONSE TO THE SECOND OFFICE ACTION

Dear Sir:

In response to the Second Office Action mailed from the Patent Office July 26, 2002, please replace and add the new claims as indicated. In addition, please replace a paragraph in the specification as indicated.

In the Specification

Please replace paragraph [0016] with the following:

**[0016]** Also, as a feature of the invention, because the cavity wall is part of the continuous substrate, it is possible to extend some circuit function into the wall. In particular, plate capacitors in the wall can serve as high frequency bypass capacitors in proximity to the die. The wall of the single unitary structure may include interleaved conductive layers forming one or more chip capacitors for high frequency bypass purposes. When the single unitary structure is formed primarily of material with moderate dielectric constant (and CTE of 5 to 9 ppm/°C) such as ceramic or glass material, conductive and insulating materials may be formed in successive thin layers to create

9/16  
11-8-02  
J. Carter

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